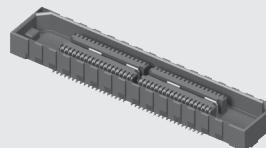


(0.635 mm) .025"

MIS-019-01-F-D



MIS-038-01-F-D



MIS-057-01-L-D

MIS SERIES

MIXED TECHNOLOGY SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?MIS

Insulator Material: Liquid Crystal Polymer

Contact Material: Phosphor Bronze

Plating:

Au or Sn over

50 μ " (1.27 μ m) Ni

Operating Temp Range: -55 $^{\circ}$ C to +125 $^{\circ}$ C

Voltage Rating: 275 VAC/389 VDC

Max Cycles: 100

RoHS Compliant: Yes

PROCESSING

Lead-Free Solderable: Yes

SMT Lead Coplanarity: (0.10 mm) .004" max (019-057)

Board Stacking:

For applications requiring more than two connectors per board contact ipg@samtec.com

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



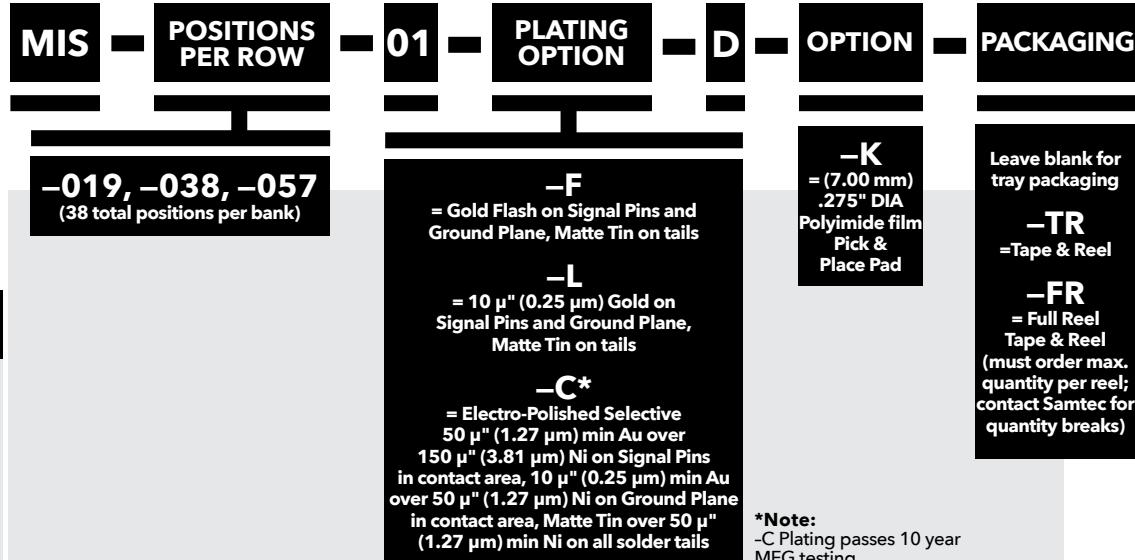
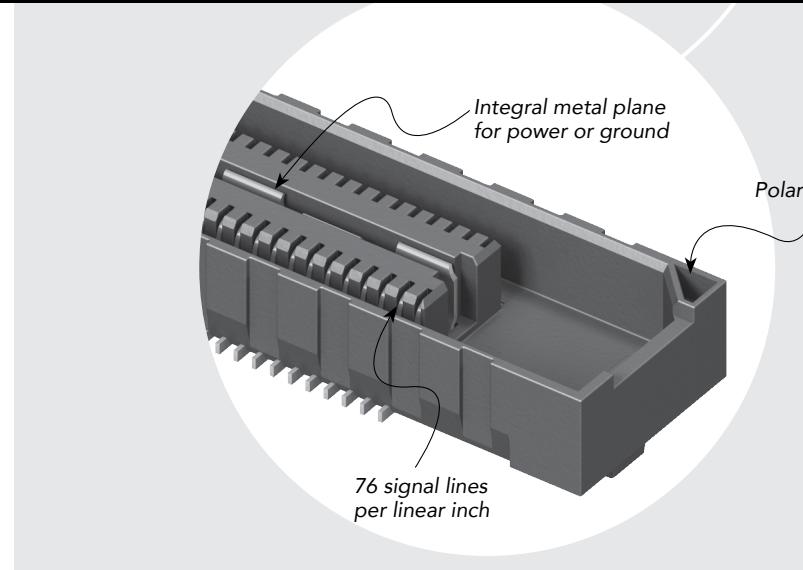
ALSO AVAILABLE

Contact Samtec

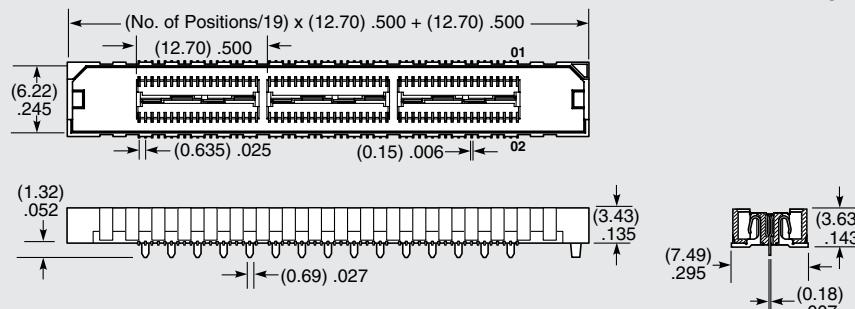
- 11 mm, 16 mm, 18.75 mm and 22 mm stack height
- 30 μ " (0.76 μ m) Gold
- Differential Pair and "Partitionable" (combine differential & single-ended banks in same connector) available.
- 76, 95, 114 and 133 positions per row

Board Mates:
MIT

Standoffs:
SO



Note:
-C Plating passes 10 year MFG testing



MATED HEIGHT*		
MIS LEAD STYLE	MIT LEAD STYLE	
-01	-02	
-01	(5.00) .197	(8.00) .315

*Processing conditions will affect mated height. See SO Series for board space tolerances.

Note: Rugged through-hole ground plane soldered to board (requires paste-over-hole, not press-fit) for added retention to PCB.